# **Amplifier Transistors**

# **NPN Silicon**

#### **Features**

• These are Pb-Free Devices

## **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V <sub>CEO</sub>	45	Vdc
Collector - Base Voltage	V <sub>CBO</sub>	50	Vdc
Emitter – Base Voltage	V <sub>EBO</sub>	5.0	Vdc
Collector Current – Continuous	Ic	800	mAdc
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	625 5.0	mW mW/°C
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	1.5 12	W mW/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

## THERMAL CHARACTERISTICS

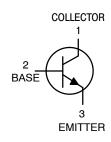
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	°C/W

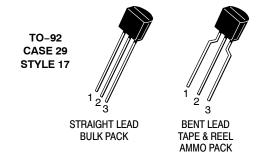
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



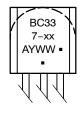
# ON Semiconductor®

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## **MARKING DIAGRAM**



BC337-xx = Device Code

(Refer to page 4)
= Assembly Location

A = Assembly Location
Y = Year
WW = Work Week
• Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	OFF CHARACTERISTICS					,
Collector – Emitter Breakdown Voltage ( $I_C = 10 \text{ mA}, I_B = 0$ )		V <sub>(BR)CEO</sub>	45	_	_	Vdc
Collector – Emitter Breakdown Voltage ( $I_C$ = 100 $\mu$ A, $I_E$ = 0)		V <sub>(BR)CES</sub>	50	-	_	Vdc
Emitter – Base Breakdown Voltage ( $I_E = 10 \mu A, I_C = 0$ )		V <sub>(BR)EBO</sub>	5.0	-	_	Vdc
Collector Cutoff Current (V <sub>CB</sub> = 30 V, I <sub>E</sub> = 0)		I <sub>CBO</sub>	-	-	100	nAdc
Collector Cutoff Current (V <sub>CE</sub> = 45 V, V <sub>BE</sub> = 0)		I <sub>CES</sub>	-	-	100	nAdc
Emitter Cutoff Current (V <sub>EB</sub> = 4.0 V, I <sub>C</sub> = 0)		I <sub>EBO</sub>	-	-	100	nAdc
ON CHARACTERISTICS			•	•	•	
DC Current Gain $(I_C = 100 \text{ mA}, V_{CE} = 1.0 \text{ V})$ $(I_C = 300 \text{ mA}, V_{CE} = 1.0 \text{ V})$	BC337 BC337-25 BC337-40	h <sub>FE</sub>	100 160 250 60	- - - -	630 400 630 –	_
Base–Emitter On Voltage (I <sub>C</sub> = 300 mA, V <sub>CE</sub> = 1.0 V)		V <sub>BE(on)</sub>	-	-	1.2	Vdc
Collector – Emitter Saturation Voltage (I <sub>C</sub> = 500 mA, I <sub>B</sub> = 50 mA)		V <sub>CE(sat)</sub>	-	-	0.7	Vdc
SMALL-SIGNAL CHARACTERISTICS			•	•		-
Output Capacitance (V <sub>CB</sub> = 10 V, I <sub>E</sub> = 0, f = 1.0 MHz)		C <sub>ob</sub>	_	15	_	pF
Current – Gain – Bandwidth Product ( $I_C$ = 10 mA, $V_{CE}$ = 5.0 V, f = 100 MHz)		f <sub>T</sub>	-	210	-	MHz

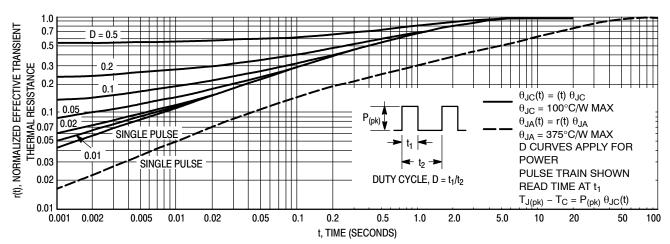


Figure 1. Thermal Response

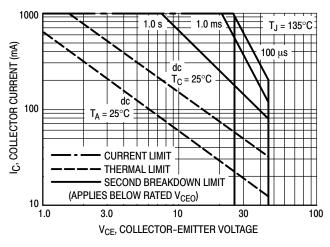


Figure 2. Active Region - Safe Operating Area

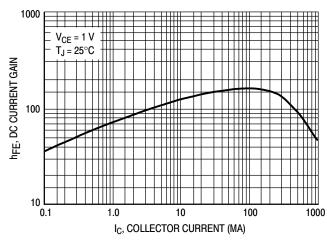


Figure 3. DC Current Gain

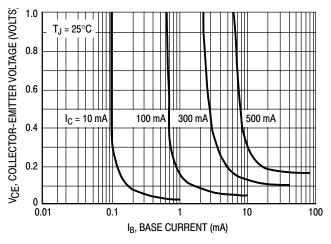


Figure 4. Saturation Region

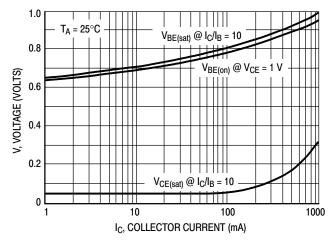


Figure 5. "On" Voltages

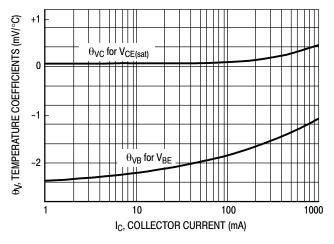


Figure 6. Temperature Coefficients

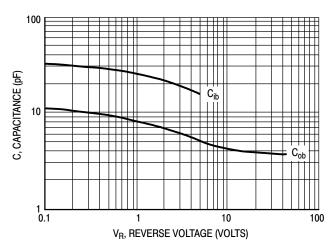


Figure 7. Capacitances

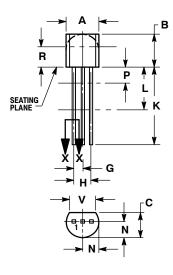
# **ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
BC337G	7		5000 Units / Bulk
BC337RL1G	7	TO-92 (Pb-Free)	2000 / Tape & Reel
BC337-025G	7–25		5000 Units / Bulk
BC337-25RL1G	7–25		2000 / Tape & Reel
BC337-25ZL1G	7–25		2000 / Ammo Box
BC337-040G	7–40		5000 Units / Bulk
BC337-40RL1G	7–40		2000 / Tape & Reel
BC337-40ZL1G	7–40		2000 / Ammo Box

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 29-11 ISSUE AM

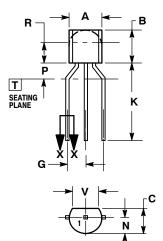


STRAIGHT LEAD **BULK PACK** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- CONTOUR OF PACKAGE BEYOND DIMENSION R
- IS UNCONTROLLED.
  LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
P	-	0.100		2.54
R	0.115		2.93	
v	0.135		3.43	



**BENT LEAD TAPE & REEL** AMMO PACK



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

- CONTROLLING DIMENSION: MILLIMETERS.
  CONTOUR OF PACKAGE BEYOND
  DIMENSION R IS UNCONTROLLED.
  LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM

	MILLIMETERS		
DIM	MIN	MAX	
Α	4.45	5.20	
В	4.32	5.33	
С	3.18	4.19	
D	0.40	0.54	
G	2.40	2.80	
J	0.39	0.50	
K	12.70		
N	2.04	2.66	
P	1.50	4.00	
R	2.93		
V	3.43		

STYLE 17:

PIN 1. COLLECTOR

BASE

**EMITTER** 

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